

<<微机电系统基础>>

图书基本信息

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内容概要

本书全面论述了微机电系统(MEMS)的基础知识,涵盖了MEMS技术的主要方面。同时引用了经典的MEMS研究论文和前沿的研究论文,为学生深入学习MEMS技术提供了指引。书中提炼出了四个典型的传感器实例:惯性传感器、压力传感器、流量传感器和触觉传感器,并介绍了利用不同原理、材料和工艺制造这些传感器的方法,既便于比较,又可以启发学生的创新意识并提高创新能力。

本书被美国伊利诺伊大学、斯坦福大学等选为教材。

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作者简介

Chang Liu (刘昶) 于1995年在美国加州理工学院获博士学位。1996年在美国伊利诺伊大学微电子实验室作博士后, 1997年成为伊利诺伊大学电气与计算机工程系以及机械与工业工程系联合任命的助理教授, 2003年获得终身职位并任副教授。

Chang Liu已经从事了14年MEMS领域的

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编辑推荐

《微机电系统基础(英文版)》被美国伊利诺伊大学、斯坦福大学等选为教材。

《微机电系统基础(英文版)》特色：均衡了不同背景的学生（机械工程系学生和电子工程系学生）的需求。

均衡地讨论了MEMS基础知识的三个支柱：设计、制造和材料。

均衡地安排了理论基础和实践。

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